

Fabrication of heat dissipating polyimide composite film

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With the rapid development of the technology, the personal devices are now being thinner and faster which producing more heat inside of the devices calls upon a great demand for new materials to efficiently dissipate the heat generated. Many researchers have conducted various studies for reducing these heat by introducing many types of fillers into polymer matrix, such as BN, CNTs, carbon materials. In this study, a polymer based thin composite film was proposed with high ratio of fillers but maintaining the flexibility of the polymer film. The newly proposed thin film with fillers showed high heat dissipating ability and good mechanical properties which can be widely applied in industries.